

N-Channel MOSFET

General Description

The WSD120N06HGDN56 is the highest performance SGT N-Channel MOSFET with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The WSD120N06HGDN56 meet the RoHS and Green Product requirement, 100% E_{AS} guaranteed with full function reliability approved.

Features

- 100% UIS Tested.
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

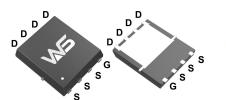
Product Summery

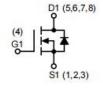
| BV _{DSS} | R _{DS(ON)} | l _D |
|-------------------|---------------------|----------------|
| 60V | 2.5mΩ | 120A |

Applications

- Power Management for Industrial DC/DC Converters
- Ldeal for high-frequency switching and synchronous rectification

DFN5*6-8L Pin Configuration





Absolute Maximum Ratings (T_A=25°C, Unless Otherwise Noted)

| Symbol | Parameter | | Rating | Units | |
|---------------------------------|--|------------------------------|------------|-------|--|
| V _{DS} | Drain-Source Voltage | | 60 | ., | |
| V _{GS} | Gate-Source Voltage | ±20 | V | | |
| . 7 | Continuous Projection Comment | T _C =25°C | 120 | | |
| I _D ⁷ | Continuous Drain Current | T _C =100°C | 96 | Α | |
| I _{DM} ³ | Pulse Drain Current | | 600 | | |
| P _D ² | Power Dissipation | T _C =25°C | 132 | W | |
| I _{AS} ³ | Single pulse Avalanche Current | | 59 | А | |
| E _{AS} ³ | Single pulse Avalanche Energy | L=0.5mH | 750 | mJ | |
| T _{STG} | Storage Temperature Range | | -55 to 150 | °C | |
| TJ | Operating Junction Temperature Range | g Junction Temperature Range | | | |
| D 14 | The survey Decision of the Archivest | t≤10s | 30 | | |
| R _{θJA} ^{1,4} | Thermal Resistance-Junction to Ambient | Steady State | 60.5 | °C/W | |
| R _{θJC} | Thermal Resistance-Junction to Case | | 0.62 | | |

WSD120N06HGDN56

N-Channel MOSFET

Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Units |
|---------------------|-----------------------------------|--|------|------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250μA | 60 | | | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V , I _D =20A | | 2.5 | 3.2 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_{D}=250\mu A$ | 2.0 | 3.0 | 3.5 | V |
| | Drain Source Leakage Current | V_{DS} =60V , V_{GS} =0V | | | 1.0 | |
| I _{DSS} | Drain-Source Leakage Current | T _J =55°C | | | 5.0 | μA |
| I _{GSS} | Gate-Source Leakage Current | V _{DS} =0V , V _{GS} =±20V | | | ±100 | nA |
| 9 _{fs} | Forward Transconductance | V_{DS} =5V , I_{D} =20A | | 50 | | S |
| R_G | Gate Resistance | f=1.0MHz | | 3.0 | | Ω |
| Q_g | Total Gate Charge (10V) | | | 80 | | |
| Q_{gs} | Gate-Source Charge | V_{DS} =30V , V_{GS} =10V , I_{D} =20A | | 13 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 14 | | |
| T _{d(on)} | Turn-On Delay Time | | | 7 | | |
| T _r | Rise Time | V_{DD} =30V , V_{GS} =10V , I_{D} =20A | | 12 | | no |
| T _{d(off)} | Turn-Off Delay Time | $R_1 = 1\Omega$, $R_{GFN} = 3\Omega$ | | 25 | | ns |
| T _f | Fall Time | J | | 4 | | |
| C _{iss} | Input Capacitance | | | 5900 | | |
| C _{oss} | Output Capacitance | V_{DS} =30V , V_{GS} =0V , f =1.0MHz | | 955 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 25 | | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Units |
|-----------------|---------------------------|--|------|------|------|-------|
| Is 7 | Continuous Source Current | | | | 120 | Α |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V , I _S =1A | | 0.7 | 1.2 | V |
| t _{rr} | Reverse Recovery Time | I _E =20A , di/dt=500A/µs | | 56 | | ns |
| Q _{rr} | Reverse Recovery Charge | 1 _F -20A , αι/αι-300A/μs | | 80 | | nC |

Note:

- The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on R_{θJA} t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 2. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- 3. Single pulse width limited by junction temperature $T_{J(MAX)}$ =150°C.
- 4. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
- 5. The static characteristics in Figures 1 to 6 are obtained using $<300\mu s$ pulses, duty cycle 0.5% max.
- 6. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150°C. The SOA curve provides a single pulse rating.
- 7. The maximum current rating is package limited.
- 8. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.
- 9. The maximum current rating is silicon limited

Typical Characteristics



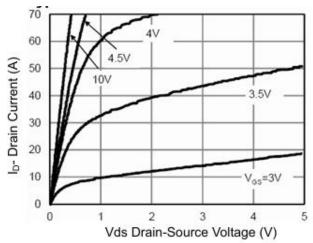


Figure 1 Output Characteristics

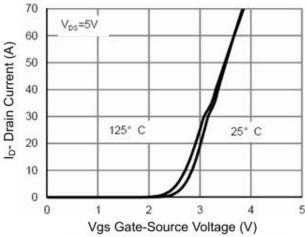


Figure 2 Transfer Characteristics

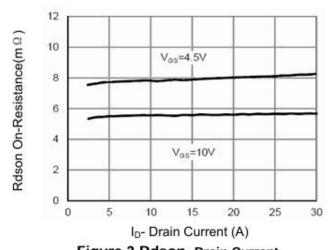


Figure 3 Rdson- Drain Current

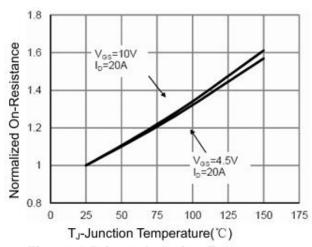
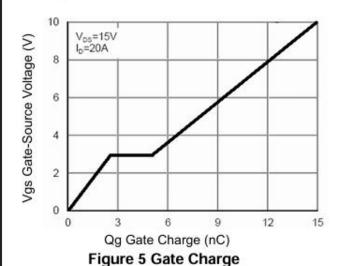


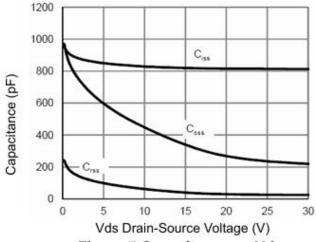
Figure 4 Rdson-Junction Temperature



1.0E+01 Very 1.0E+00 1.0E-01 1.0E-02 1.0E-03 1.0E-03 1.0E-04 1.0E-05 0.0 0.2 0.4 0.6 0.8 1.0 Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

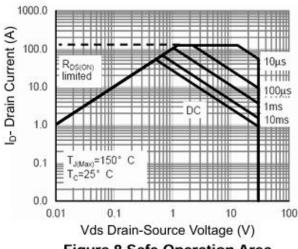




30

Figure 7 Capacitance vs Vds

Figure 9 Power De-rating



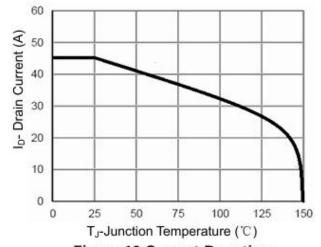


Figure 8 Safe Operation Area

Figure 10 Current De-rating

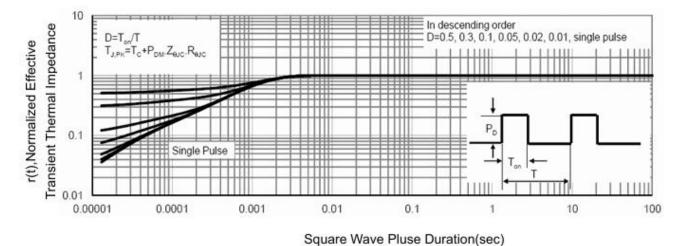
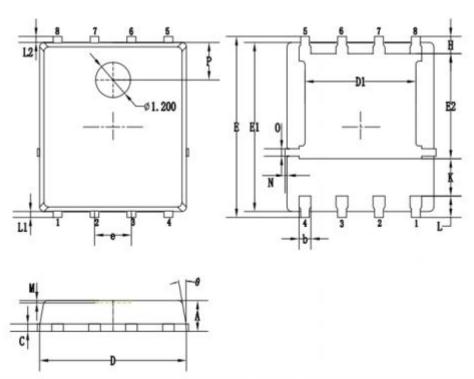


Figure 11 Normalized Maximum Transient Thermal Impedance

N-Channel MOSFET

Packaging information



| SYMBOLS | MILLIMETERS | | | |
|---------|-------------|-----------|------|--|
| | MIN. | NOM. | MAX. | |
| Α | 0.90 | 1.05 | 1.20 | |
| b | 0.35 | 0.40 | 0.50 | |
| С | 0.20 | 0.25 | 0.35 | |
| D | 4.90 | 5.05 | 5.20 | |
| D1 | 3.72 | 3.82 | 3.92 | |
| E | 6.00 | 6.15 | 6.30 | |
| E1 | 5.60 | 5.75 | 5.90 | |
| E2 | 3.47 | 3.57 | 3.67 | |
| е | 1.27 BSC. | | | |
| Н | 0.48 | 0.58 | 0.68 | |
| K | 1.17 | 1.27 | 1.37 | |
| L | 0.64 | 0.74 | 0.84 | |
| L1/L2 | | 0.20 REF. | | |
| θ | 8° | 10° | 12° | |
| M | 0.08 REF. | | | |
| N | 0 | | 0.15 | |
| 0 | 0.25 REF. | | | |
| P | 1.28 REF. | | | |



WSD120N06HGDN56

N-Channel MOSFET

Attention

- 1, Any and all Winsok power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life–support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Winsok power representative nearest you before using any Winsok power products described or contained herein in such applications.
- 2, Winsok power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Winsok power products described or contained herein.
- 3, Specifications of any and all Winsok power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- 4, Winsok power Semiconductor CO., LTD. strives to supply high–quality high–reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- 5, In the event that any or all Winsok power products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- 6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Winsok power Semiconductor CO., LTD.
- 7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Winsok power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- 8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the Winsok power product that you Intend to use.
- 9, this catalog provides information as of Sep.2014. Specifications and information herein are subject to change without notice.